



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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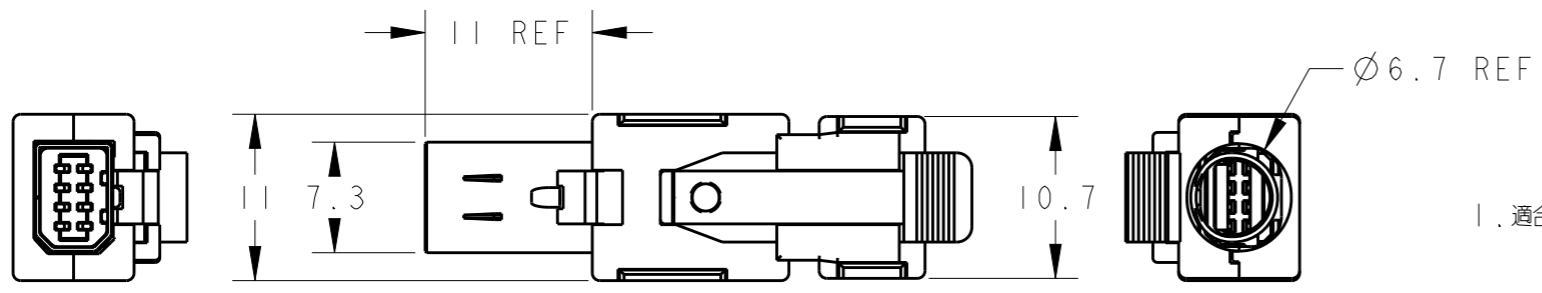
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REVISIONS				
P	LTR	DESCRIPTION	DATE	DWN APVD
	C	REVISED	01OCT2009	T.S N.Y

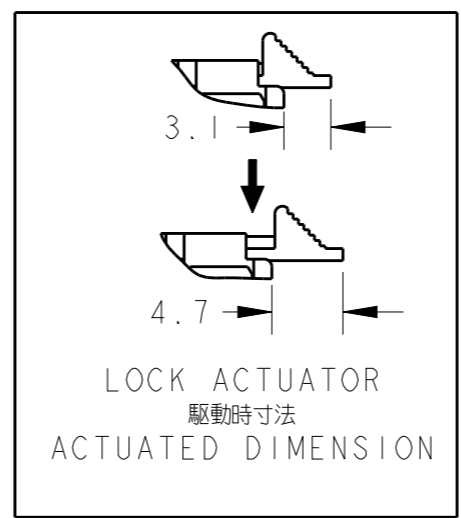
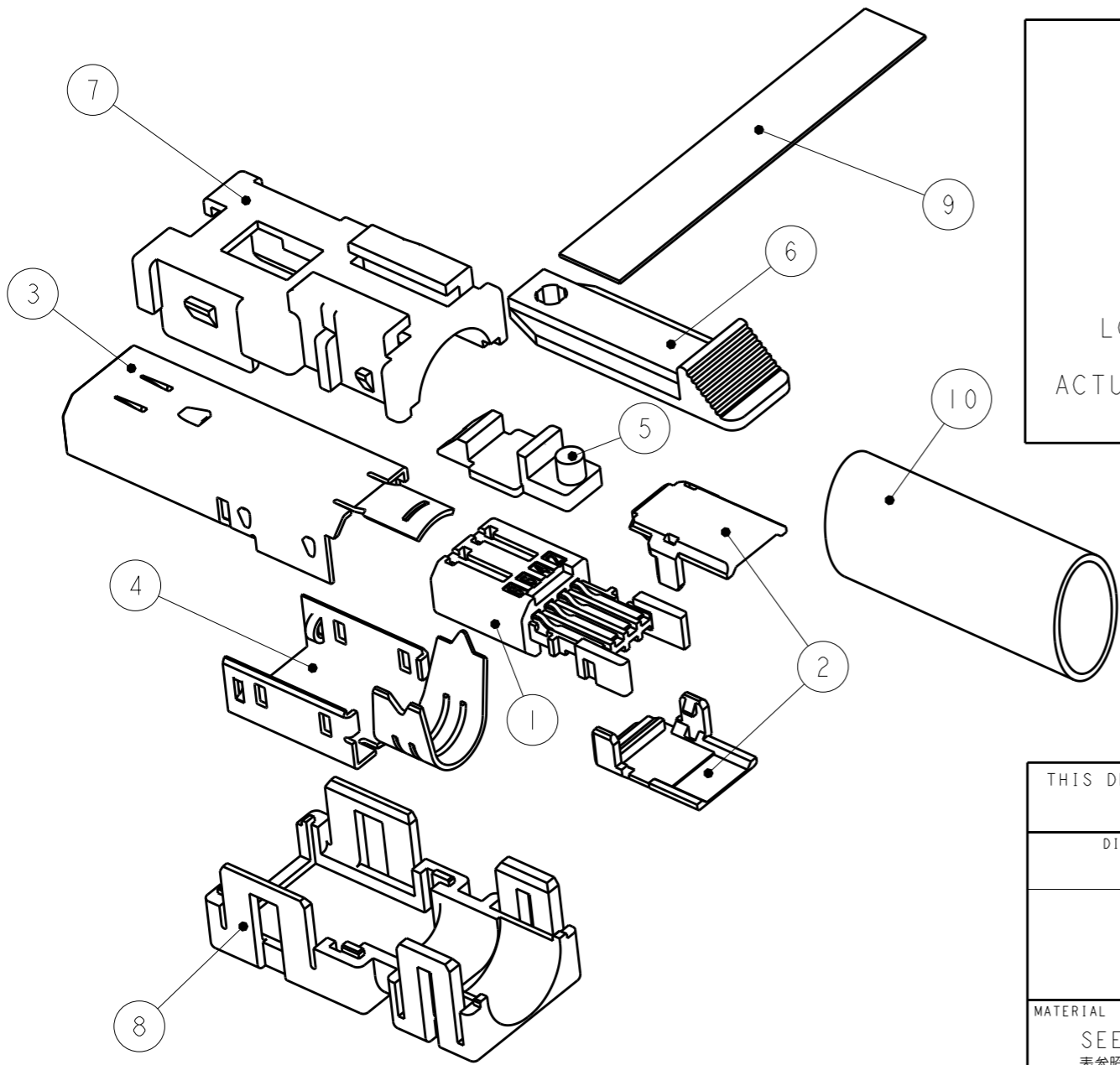
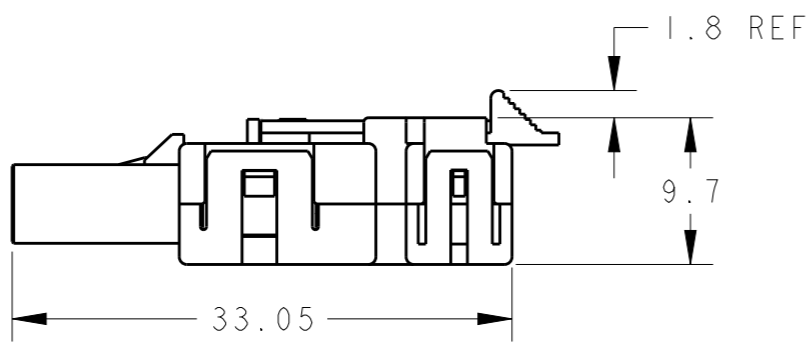


- 適合電線：推奨導体サイズAWG30~26 X 8芯
導体サイズMAX AWG22 X 4芯
仕上がり外径φ6.7 MAX
 - アートのコードは同梱の顧客図面に記載。
 - 本型番の製品は専用梱包トレーに1SETずつ個別梱包される。
なお梱包の際は、⑥を⑦に事前にASSYしてからトレーに梱包される。
1. APPLICABLE CABLE: RECOMMENDED AWG30~26 X 8C
MAX AWG22 X 4C
OVERALL DIAMETER 6.7MAX.
2. DATE CODE IS DESCRIBED ON THE BUNDLED CUSTOMER DRAWING.
3. THE PRODUCT OF THIS DRAWING NO. IS PACKED INDIVIDUALLY IN PACKAGE OF EXCLUSIVE USE.
BEFORE THIS KIT IS PACKED TO TRAY, ⑥ SHOULD BE ASSEMBLED TO ⑦.

D-SHAPE TYPE I



回路番号
CIRCUIT NO.



QTY.	MATERIAL / FINISH 材料 / 仕上げ	PART NAME 部品名称	ITEM NO.
1	CROSS-LINKED POLYOLEFIN 架橋ポリオレフィン	HEAT SHRINKABLE TUBE 熱収縮チューブ	⑩
1	ELECTROLYSIS COPPER FOIL, ACRYLIC ADHESIVE MATERIAL 電解銅箔 アクリル系粘着材	COPPER FOIL TAPE 銅箔テープ	⑨
1	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	BOTTOM COVER ボトムカバー	⑧
1	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	TOP COVER, EJECTOR EXT VER. トップカバー エジェクタ延長バージョン	⑦
1	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	PLUG LOCK ACTUATOR ロックエジェクタ作動体	⑥
1	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	LOCK EJECTOR EXT VER. ロックエジェクタ延長バージョン	⑤
1	STEEL/UNDER:Cu PLATING, TOP:Ni PLATING 鋼/下地:Cuめっき, 表面:Niめっき	BOTTOM SHELL ボトムシェル	④
1	STEEL/UNDER:Cu PLATING, TOP:Ni PLATING 鋼/下地:Cuめっき, 表面:Niめっき	TOP SHELL トップシェル	③
2	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	PLUG HSG COVER プラグハウジングカバー	②
1	CONTACT: COPPER ALLOY UNDER ALL SURFACE: Ni PLATING 1.27μmMIN TOP CONTACT AREA: Au PLATING: 0.5μmMIN SOLDERING AREA: Au FLASH HSG: POLY-AMID OF GLASS FILLED THERMO PLASTIC(UL94V-0) コンタクト: 銅合金 下地: 全面Niめっき1.27μm以上 表面: 接点部Auめっき0.5μm以上 はんだ付け部Auフラッシュめっき ハウジング: ガラス入りポリアミド系熱可塑性樹脂(UL94V-0)	PLUG HSG SUB ASSY プラグハウジングサブアセンブリ	①

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED: ±0.3
	0-PLC ±
	1-PLC ±
	2-PLC ±
	3-PLC ±
	4-PLC ±
	ANGLES ±
MATERIAL SEE TABLE 表参照	FINISH SEE TABLE 表参照

DWN 03DEC2008 S. INOMATA
 CHK 03DEC2008 A. OOISHI
 APVD 03DEC2008 A. OOISHI

TE Connectivity

NAME
INDUSTRIAL MINI I/O
PLUG CONNECTOR KIT D-SHAPE TYPE I,
LOCK EJECTOR EXTEND VERSION

PRODUCT SPEC 108-78405
 APPLICATION SPEC 114-5431

WEIGHT -

SIZE A3 CAGE CODE 00779 DRAWING NO. C-2069250 RESTRICTED TO -

Customer Drawing SCALE NON SHEET 1 OF 1 REV C